

# WP616 Solder Paste

Lead-Free, Water Soluble, Zero-Halogen

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## Product Description

Kester WP616 Solder Paste is a zero-halogen, lead-free, water soluble solder paste formula for both nitrogen and air reflow applications. WP616 provides a combination of consistent print performance at wide humidity levels, excellent solderability and ease of cleaning, while maintaining a zero-halogen flux formulation. WP616 is a stable water soluble formula, providing consistent stencil life, tack time and print definition. WP616 is classified as ORM0 flux under IPC J-STD-004B.

## Performance Characteristics:

- Superior reflow characteristics
- Classified as ORM0 per J-STD-004B
- Excellent activity and printability
- Zero-Halogen (none intentionally added)
- Wide reflow profile window with good solderability
- Reflowable in air and nitrogen conditions
- Cleaning can be accomplished with heated deionized water

## RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive. Additional RoHS information is located at <https://www.kester.com/downloads/environmental>.

## Physical Properties

(SAC 305 and SnAg, T4)

**Viscosity (typical):** 1700 poise  
Malcom Viscometer @ 10 rpm and 25 °C

**Slump Test:** Pass  
Tested to J-STD-005, IPC-TM-650, Method 2.4.35

**Solder Ball Test:** Pass  
Tested to J-STD-005, IPC-TM-650, Method 2.4.43

**Wetting:** Pass

Tested to J-STD-005, IPC-TM-650, Method 2.4.45

**Reliability Properties****Copper Mirror:** M

Tested to J-STD-004B, IPC-TM-650, Method 2.3.32

**Copper Corrosion:** L

Tested to J-STD-004B, IPC-TM-650, Method 2.6.15

**Halogen Content:** None Detected

Tested to J-STD-004B, IPC-TM-650, Method 2.3.41

**Electrochemical Migration (ECM):** Pass

Tested to J-STD-004B, IPC-TM-650, Method 2.6.14.1

**Surface Insulation Resistance (SIR):** Pass

Tested to J-STD-004B, IPC-TM-650, Method 2.6.3.7

Test Conditions: 40 °C, 90% RH, 7 days, 12.5V

**Availability**

Standard alloy availability for WP616 is Sn96.5Ag3.0Cu0.5 with Type 3 (T3), Type 4 (T4) and Type 5 (T5) powder size distribution. T4 mesh size is recommended for standard and fine pitch applications. T5 is recommended for ultra-fine pitch applications. WP616 is also compatible with other SnAgCu and SnAg alloys in similar melting range to the listed alloy. For specific packaging information, refer to Kester's Solder Paste Packaging Chart for available sizes. The appropriate alloy and powder size combination depends on the process variables and the specific application. If you are looking for alloy or powder sizes currently not listed on Kester's Solder Paste Packaging Chart, please contact your Kester Sales or Technical Representative.

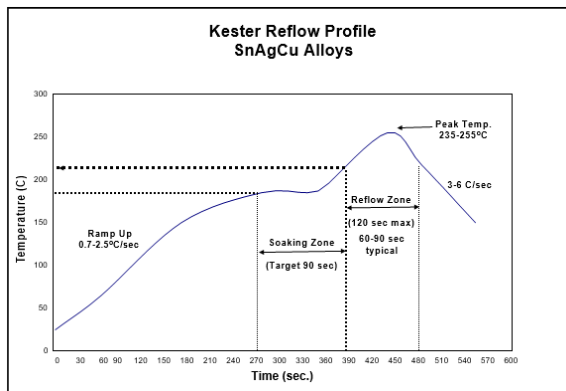
**Printing Parameters**

Below are process guidelines, and it is advisable to note that the optimum setting for a given assembly may vary and this is dependent on the circuit board design, board thickness, components used, and equipment used. A design of experiments is recommended to be done to optimize the soldering process. In addition, incoming solderability inspection of circuit boards and components is recommended as part of process control to maintain consistent soldering performance and electrical reliability.

<b>Print Temperature Window</b>	20 to 30 °C (68 to 86 °F) / 30 to 65% RH
<b>Squeegee Angle</b>	60° from horizontal
<b>Speed</b>	25 to 200 mm/sec (1 to 8 in/sec)
<b>Pressure<sup>1</sup></b>	0.18 to 0.27 kg/cm (1 to 1.5 lb/in)
<b>Separation Speed</b>	5 to 20 mm/sec
<b>Stencil life</b>	8 hours at 21 to 24 °C (70 to 75 °F) / 40 to 45% RH

<sup>1</sup> Pressure should be increased with increasing print speed. First set the print speed. Then set the pressure to the minimum required to clean the solder paste off of the stencil.

## Recommended Reflow Profile



The recommended reflow profile for formula made with SAC and SnAg alloys is shown here. This profile is simply a guideline. WP616 has excellent solderability and wetting across a wide range of profiles, with similar performance in air and nitrogen. Your optimal profile may be different from the one shown based on your oven, board and mix of defects. Contact Kester Technical Support if you need additional profiling advice.

## Cleaning

WP616 is a water soluble formula. Its residues are best removed using automated cleaning equipment (in-line or batch). Deionized water heated to 60 to 75 °C (140 to 165 °F) should be used followed by a final rinse with deionized water. It is recommended to clean the circuit board after each reflow cycle. Commercial cleaning agent can be used. Contact your supplier for recommendations.

## Storage, Handling and Shelf Life

WP616 has a six-month shelf life when refrigerated. Refrigeration (0 to 10 °C/32 to 50 °F) is the recommended storage condition for solder paste to maintain consistent viscosity, reflow characteristics and overall performance. WP616 should be stabilized at room temperature prior to printing. Please contact Kester Technical Support if you require additional advice with regards to handling and storage of this material.

## Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product. Safety Data Sheets are available at <https://www.kester.com/downloads/sds>.

## Contact Information

To confirm this document is the most recent version, please contact [Assembly@MacDermidAlpha.com](mailto:Assembly@MacDermidAlpha.com)

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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

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